January 20, 1997 Volume 28 Number 3

CURRENT CONTENTS®

Engineering, Computing & Technology

INCLUDING

Acoustics • Aerospace • Artificial Intelligence • Automation

Chemical Engineering • Civil Engineering • Computer-aided Engineering

Computer Hardware & Software • Computing Systems & Networks

Electrical & Electronics Engineering • Engineering Management • Energy

Environmental Engineering • Fuels • Geotechnology • Information Technology

Instrumentation • Lasers • Manufacturing • Materials • Mechanical Engineering

Mechanics • Metallurgy • Microelectronics • Mining • Neurocomputing

Operations Research • Optics • Optoelectronics • Polymers • Process Industries

Robotics • Semiconductors • Superconductors

Signal & Image Processing • Telecommunications

ISI℠
Institute for Scientific Information℠
3501 Market Street, Philadelphia, PA 19104 U.S.A.

VOLUME
28
NUMBER
03

January 20, 1997

Not all journals covered by ***Current Contents*** are published weekly. Therefore, in any given issue your favorite journal may not be listed. However, it will be included as often as it is issued. For the complete List of Serials covered and the latest Publisher Guide see issue #1, January 6, 1997. For the latest Triannual Cumulative Index see issue #38, September 16, 1996.

FEATURED IN THIS ISSUE OF *CURRENT CONTENTS®/ENGINEERING, COMPUTING & TECHNOLOGY*

FEATURES

DISCIPLINE GUIDE

INDEXES

Current Contents processes all journal issues within two weeks of their receipt and makes every reasonable effort to insure their prompt delivery to ISI. Please note that the cover dates of some journals do not correspond to the actual publication dates.

If a journal is covered in more than one ***CC*®**, a letter code appears in parentheses next to the volume and issue number to identify which editions: (L)=Life Sciences; (P)=Physical, Chemical & Earth Sciences; (S)=Social & Behavioral Sciences; (A)=Agriculture, Biology & Environmental Sciences; (C)=Clinical Medicine; (E)=Engineering, Computing & Technology; (H)=Arts & Humanities.

JOURNALS APPEARING IN THIS ISSUE:

32	ACM SIGPLAN NOTICES,31 (12)
134	ACUSTICA,82 (6)
18	ADHES AGE,39 (13)
8	AEROSP AM,34 (12)
19	AICHE J,42 (12)
62	AMBIO,25 (7)
79	AMER CERAM SOC BULL,75 (12)
59	ANN MATH ARTIF INTELL,18 (1)
9	APPL ARTIF INTELL,10 (6)
59	APPL COMPUT HARMONIC ANAL,3 (4)
60	APPL MATH MODEL,20 (12)
111	APPL THERM ENG,17 (2)
111	ASHRAE J-HEAT REFRIG AIR-COND,38 (12)
125	ATW-INT Z KERNENERG,41 (11)
10	AUTOMATICA,32 (11)
62	BIOCYCLE,37 (12)
69	BULL CAN PETROL GEOL,44 (4)
33	BYTE,22 (1)
80	CELL CHEM TECHNOL,30 (1-2)
80	CELL CHEM TECHNOL,30 (3-4)
81	CELL POLYM,15 (6)
81	CEM CONCR RES,26 (12)
60	CHAOS SOLITON FRACTAL,7 (10)
60	CHAOS SOLITON FRACTAL,7 (11)
20	CHEM ENG,103 (12)
21	CHEM ENG LONDON,1996 (623)
22	CHEM ENG PROCESS,35 (6)
22	CHEM ENG PROGR,92 (12)
82	CHEM MATER,8 (12)
23	CHEM WEEK,158 (49)
24	CHEM-ING-TECH,68 (11)
69	CIM BULL,89 (1005)
38	CIRC SYST SIGNAL PROCESS,16 (1)
61	COMMUN NUMER METHODS ENG,12 (12)
83	COMPOS PART B-ENG,27 (6)
112	COMPUT FLUIDS,25 (8)
34	COMPUT IND,32 (1)
112	COMPUT METHOD APPL MECH ENG,138 (1-4)
10	CONTROL ENG,43 (18)
25	DENKI KAGAKU,64 (12)
28	EARTHQUAKE ENG STRUC DYNAM,26 (1)
38	EDN,41 (26)
39	ELECTRON DES,44 (26)
40	ELECTRON PROD MAG,39 (7)
70	EMJ-ENG MINING J,197 (12)
64	ENERG SOURCE,18 (7)
113	ENG FRACTURE MECH,55 (6)
64	ENVIRON PROG,15 (4)
113	EXP FLUID,22 (1)
114	EXP FLUID,22 (2)
114	EXP THERM FLUID SCI,13 (4)
11	EXPERT SYSTEMS,13 (4)
115	FORSCH INGENIEURW,62 (11-12)
40	GEC J RES,13 (3)
65	GEFAHRST REINHALT LUFT,56 (12)
70	GEOTECHNIQUE,46 (4)
84	GLASTECH BER-GLASS SCI TECHN,69 (11)
84	HOLZ ROH WERKST,54 (6)
53	HUM FACTORS,38 (4)
35	IBM J RES DEVELOP,40 (6)
41	IEE REVIEW,42 (6)
74	IEEE ACM TRANS NETWORKING,4 (6)
42	IEEE ELECTRON DEV LETT,18 (1)
42	IEEE MICROW GUIDED WAVE LETT,7 (1)
75	IEEE PERSONAL COMMUN,3 (6)
42	IEEE TRANS APPL SUPERCONDUCT,6 (3)
11	IEEE TRANS AUTOMAT CONTR,41 (12)
43	IEEE TRANS CIRCUIT SYST-I,43 (12)
35	IEEE TRANS COMPUT,45 (12)
43	IEEE TRANS ELECTRON DEVICES,44 (1)
45	IEEE TRANS MICROWAVE THEORY,44 (12)P1
46	IEEE TRANS MICROWAVE THEORY,44 (12)P2
12	IEEE TRANS PATT ANAL MACH INT,18 (12)
12	IEEE TRANS SYST MAN CYBERN A,27 (1)
13	IEEE-ASME TRANS MECHATRON,1 (1)
13	IEEE-ASME TRANS MECHATRON,1 (2)

CONTINUED

CONTINUED

14	IEEE-ASME TRANS MECHATRON,1 (3)
14	IEEE-ASME TRANS MECHATRON,1 (4)
53	IIE TRANSACTIONS,28 (12)
54	INDIAN J ENG MATER SCIENCES,3 (6)
75	INFOR,34 (4)
75	INFORM PROCESS MANAGE,32 (6)
76	INSTRUM EXP TECH-ENGL TR,39 (5)
14	INT J ADAPT CONTROL SIGNAL PR,10 (6)
54	INT J ADV MANUF TECHNOL,12 (5)
36	INT J COMPUT APPL TECHNOL,9 (5-6)
65	INT J HYDROGEN ENERG,21 (11-12)
48	INT J INFRAR MILLIM WAVE,17 (12)
115	INT J MACH TOOL MANUF,36 (12)
48	INT J MICROWAVE MILLIMETER-W,7 (1)
61	INT J NUMER METHOD ENG,40 (1)
15	INT J ROBUST NONLINEAR CONTR,6 (9-10)
115	INT J VEH DES,17 (5-6)
36	INTEGRATION,21 (1-2)
121	ISIJ INT,36 (12)
8	IZV VYSSH UCH ZAV AVIA,1996 (3)
49	IZV VYSSH UCH ZAV RADIOELEKTR,39 (9-10)
84	J ADHES SCI TECHNOL,10 (12)
85	J ADV MATER,28 (1)
67	J AGR ENG RES,65 (4)
67	J AIR WASTE MANAGE ASSOC,46 (12)
28	J AMER WATER WORK ASSN,88 (12)
85	J APPL POLYM SCI,63 (1)
15	J ARTIF INTELL RES,5 (1996)
86	J CERAMIC SOC JPN,104 (12)
49	J ELECTROMAGNET WAVE APPLICAT,10 (11)
116	J ENG MECH-ASCE,123 (1)
68	J ENVIRON ENG-ASCE,123 (1)
116	J FLUID MECH,327 (NOV 25)
29	J HYDRAUL ENG-ASCE,123 (1)
15	J INTELL ROBOT SYST,17 (3)
87	J MATER CHEM,6 (12)
117	J MATER PROCESS TECHNOL,61 (4)
88	J MATER SCI,31 (23)
16	J MATH IMAGING VISION,6 (4)
117	J MECH PHYS SOLIDS,44 (12)
50	J MICROELECTROMECHANICAL SYST,5 (4)
118	J NON-NEWTONIAN FLUID MECH,67 (NOV)
54	J OPER RES SOC,47 (12)
135	J OPT SOC AM A-OPT IMAGE SCI,13 (12)
50	J POWER SOURCES,62 (1)
89	J PULP PAP SCI,22 (12)
55	J RES NATL INST STAND TECHNOL,101 (5)
136	J SOUND VIB,198 (4)
29	J STRUCT ENG-ASCE,123 (1)
30	J TRANSP ENG-ASCE,123 (1)
30	J WATER RESOUR PLAN MAN-ASCE,123 (1)
30	J WATER SUPPLY RES TECHNOL-A,45 (6)
31	J WATERW PORT COAST OC-ASCE,123 (1)
90	KAUT GUMMI KUNSTST,49 (11)
27	KOREAN J CHEM ENG,13 (6)
90	KUNSTST-PLAST EUR,86 (11)
16	LAB ROBOTICS AUTOMATION,8 (5)
71	MAR GEORESOUR GEOTECHNOL,14 (4)
31	MAR TECHNOL SOC J,30 (3)
91	MATER EVAL,54 (12)
91	MATER LETT,29 (1-3)
92	MATER RES BULL,32 (1)
93	MATER SCI ENG A-STRUCT MATER,217 (OCT 30)
97	MATER SCI ENG A-STRUCT MATER,219 (1-2)
98	MATER SCI ENG B-SOLID STATE M,41 (2)
98	MECH MATER,24 (3)
51	MICROELECTRON REL,37 (2)
71	MINER ENG,9 (12)
99	MRS BULL,21 (12)
36	MULTIMEDIA SYST,4 (6)
72	NEFTYANOE KHOZYAISTVO,1996 (9)
16	NETWORK-COMPUT NEURAL SYST,7 (4)
37	NEW GENERATION COMPUT,15 (1)
55	NEW SCI,152 (2060)
118	NONLINEAR DYNAMICS,11 (3)
126	NUCL ENG DES,167 (1)
126	NUCL INSTRUM METH PHYS RES A,381 (2-3)
128	NUCL INSTRUM METH PHYS RES A,382 (1-2)
130	NUCL INSTRUM METH PHYS RES B,120 (1-4)
133	NUCL TECHNOL,117 (1)
73	OIL GAS J,94 (50)
73	OIL GAS J,94 (51)
57	OPER RES,44 (6)
136	OPT COMMUN,133 (1-6)
140	OPTIK,104 (2)
99	PAPIER,50 (11)
37	PARALLEL COMPUT,22 (10)
27	PARTICULATE SCI TECHNOLOGY,14 (3)
17	PATT RECOG,29 (12)
17	PATTERN RECOGNITION LETT,17 (13)
99	PLAST ENG,52 (12)
119	PMM J APPL MATH MECH-ENGL TR,60 (3)
100	POLYM COMPOSITE,17 (6)
101	POLYM ENG SCI,36 (23)
101	POWDER TECHNOL,89 (2)
32	PROC INST CIVIL ENG-WATER MAR,118 (4)
134	RADIAT PROT DOSIM,68 (1-2)
58	RELIAB ENG SYST SAFETY,54 (1)
119	REV GEN THERM,35 (416)
122	REV METALL-CAH INF TECH,93 (11)
101	RUBBER CHEM TECHNOL,69 (4)
123	RUSS MET-ENGL TR,1996 (3)
58	SAF SCI,24 (1)
124	SCRIPTA MATER,36 (2)
78	SENSOR ACTUATOR A-PHYS,55 (1)
78	SENSOR ACTUATOR A-PHYS,55 (2-3)
120	SHOCK WAVES,6 (5)
76	SIGNAL PROCESS,55 (1)
68	SOLAR ENERG,58 (4-6)
52	SOLID STATE ELECTRON,39 (12)
18	SYST CONTROL LETT,29 (3)
102	TAPPI J,79 (12)
103	TEXT CHEM COLOR,28 (12)
120	THEOR APPL FRACT MECH,25 (3)
37	THEOR COMPUT SCI,169 (1)
38	THEOR COMPUT SCI,169 (2)
104	THIN SOLID FILMS,286 (1-2)
106	THIN SOLID FILMS,287 (1-2)
108	THIN SOLID FILMS,288 (1-2)
124	TRANS INST MET FINISH,74 (NOV)P6
32	TRANSPORT RES C-EMERG TECHNOL,4 (3)
32	TRANSPORT RES C-EMERG TECHNOL,4 (4)
58	TRAV HUM,59 (4)
120	VACUUM,47 (12)
121	VEH SYST DYN,26 (6)
110	ZKG INT,49 (11)

Journal Coverage Changes

Current Contents®/Engineering, Computing & Technology,

Issue #3, January 20, 1997

(ISI® abbreviated titles appear in parentheses following the full title for all newly added or changed journal titles.)

The following journal has been added:

IEEE—ASME Transactions on Mechatronics (IEEE-ASME TRANS MECHATRON) ISSN 1083-4435, IEEE—Institute of Electrical and Electronics Engineers, Inc., 345 East 47th Street, New York, NY 10017-2394, Quarterly, Price Available Upon Request.